## Wen Yueh

## List of Publications by Year in descending order

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2258059 1872680 41 8 3 6 citations h-index g-index papers 8 8 8 49 docs citations citing authors all docs times ranked

#	Article	IF	CITATIONS
1	Active Fluidic Cooling on Energy Constrained System-on-Chip Systems. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 1813-1822.	2.5	8
2	Design, Characterization, and Application of a Field-Programmable Thermal Emulation Platform. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 1330-1339.	2.5	1
3	Thermally Adaptive Cache Access Mechanisms for 3D Many-Core Architectures. IEEE Computer Architecture Letters, 2016, 15, 129-132.	1.5	3
4	Experimental characterization of in-package microfluidic cooling on a System-on-Chip. , 2015, , .		3
5	A Memory-Based Logic Block With Optimized-for-Read SRAM for Energy-Efficient Reconfigurable Computing Fabric. IEEE Transactions on Circuits and Systems II: Express Briefs, 2015, 62, 593-597.	3.0	8
6	Post-Silicon Estimation of Spatiotemporal Temperature Variations Using MIMO Thermal Filters. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 650-660.	2.5	3
7	Enhancement in CMOS chip performance through microfluidic cooling. , 2014, , .		11
8	Performance and Robustness of 3-D Integrated SRAM Considering Tier-to-Tier Thermal and Supply Crosstalk. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 943-953.	2.5	4